Printed Pag	~	ubject Code:- A	MTVL0101		
	R	oll. No:			ſ
	NOIDA INSTITUTE OF ENGINEEDING AN	D TECHNOLO	CV CDEAT	ED NOIDA	
	NOIDA INSTITUTE OF ENGINEERING AN (An Autonomou		GI, GREAI	ER NOIDA	
	Affiliated to Dr. A.P.J. Abdul Kalam Technic M.Tec	cal University, U	Jttar Pradesh,	Lucknow	
	SEM: I - THEORY EXAMIN Subject: CMOS Digit	,	,		
Time: 03	3:00 Hours			Max. M	arks: 70
General In	structions:				
1. All o	questions are compulsory. It comprises of three S	ections A, B an	d C.		
shor • Sect • Sect	tion A - Question No- 1 is objective type quest to type questions carrying 2 marks each. tion B - Question No- 3 is Long answer type - I question C - Question No- 4 to 8 are Long answer typesheet should be left blank. Any written material a	uestions carryin e - II questions	g 4 marks eac carrying 7 ma	ch. rks each.	·
	SECTION A			15	
1. Attempt	all parts:-				
1-a.	The enhancement type basically termed as a (CO1)	normally-OFF	N MOSFET	works only wi	th 1
	1. large positive gate voltage				
	2. large negative gate voltage				
	3. large positive drain voltage				
	4 large negative drain voltage				
1-b.	In CMOS fabrication, nMOS and pMOS are int	egrated in same	substrate. (Co	O2)	1
	1. a) true				
	2. b) false				
1-c.	The boolean function Y=AB+CD is to be reminimum number of gates required is (CC		nly 2 input N	NAND gates. The	he 1
	1. 2				
	2. 3				
	3. 4				
4 1	4. 5			(T) (T) (GO 1)	
1-d.	In precharge phase, when capacitor is fully char	ge it becomes e	qual to V _{DD} .	(T/F) (CO4)	1
	1. TRUE				
4	2. FALSE		•. 1		
1-e.	Which of the following memories uses one trar (CO5)	sistor and one	capacitor as b	asic memory un	it 1
	1. SRAM				
	2. DRAM				
	3. Both				
2. 4	4. None				
2. Attempt	<u>.</u>				
2-a.	Explain the three regions of operation of a MOS				2
2-b.	Compare between CMOS and bipolar technolog	gies. (CO2)			2

2-c.	Draw CMOS diagram of the function $Y=(A.(B+C))'$ (CO3)	2		
2-d.	What is pass transistor? (CO4)	2		
2-e.	Differentiate between SRAM and DRAM. (CO5)	2		
	SECTION B 20			
3. Answe	er any <u>five</u> of the following:-			
3-a.	Explain the energy band diagram for combined MOS system and elaborate why there is bending near the oxide semiconductor interface? (CO1)	4		
3-b.	Explain accumulation, depletion, inversion regions of operation in case externally biased MOS structure.(CO1)			
3-c.	Explain briefly the scaling in VLSI. (CO2)	4		
3-d.	What is switching power dissipation of CMOS inverter? (CO2)	4		
3-е.	Draw CMOS diagram of the function Y=(A.B+C). (D+E))' (CO3)	4		
3-f.	Explain synchronous dynamic circuit techniques with neat diagrams.(CO4)	4		
3-g.	What is DRAM? Explain DRAM with the diagram.(CO5)	4		
	SECTION C 35			
4. Answe	er any <u>one</u> of the following:-			
4-a.	What is channel length modulation? Calculate effective channel length and new drain current.(CO1)			
4-b.	Define Noise immunity and Noise margins. Calculate VOH, VOL, VIL, VIH for a depletion-load nMOS Inverter. Explain why we don't use enhancement-load nMOS inverter? (CO1)			
5. Answe	er any <u>one</u> of the following:-			
5-a.	What is CMOS inverter? Draw the voltage transfer curve (VTC) and explain. (CO2)	7		
5-b.	What is threshold voltage for CMOS inverter? Calculate Noise margin for CMOS inverter. (CO2)	7		
6. Answe	er any <u>one</u> of the following:-			
6-a.	Explain the design of CMOS Full Adder with the help of a neat diagram. (CO3)	7		
6-b.	Draw and explain the D FF design with the help of transmission gate. (CO3)	7		
7. Answe	er any <u>one</u> of the following:-			
7-a.	What is dynamic CMOS transmission gate logic? Explain it with two different stages and also explain the working of soft node. (CO4)	7		
7-b.	Differentiate between synchronous and asynchronous sequential circuits? What are the synchronous dynamic circuit techniques? (CO4)	7		
8. Answe	er any <u>one</u> of the following:-			
8-a.	Distinguish between NOR flash memory cell and NAND flash memory cell. (CO5)	7		
8-b.	What do you mean by static RAM. Explain the Read and Write operations of 6 Transistor SRAM cell with a neat diagram (CO5)	7		